BMA250

Digital, triaxial acceleration sensor

Handling, soldering & mounting instructions

Bosch Sensortec

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BMA250 Handling, soldering & mounting instructions

Ordering code	Please contact your Bosch Sensortec representative for the ordering code
Package type	12-pin LGA
Document revision	1.1
Document release date	21 January 2011
Document number	BST-BMA250-HS000-01
Technical reference code(s)	0 273 141 087, 0 273 141 121
Notes	Data in this document are subject to change without notice. Product photos and pictures are for illustration purposes only and may differ from the real product's appearance. Proprietary information, not intended for publication.

Handling, soldering & mounting instructions for the BMA250

This document describes the conditions and parameters to be applied when handling, soldering and mounting the BMA250 to a PCB.

Important:

- In order to avoid any damages of the BMA250 and resultant loss of warranty please strictly keep with the instructions described within this document.

- It is also strongly recommended to study the BMA250 (preliminary) data sheet prior to handling the BMA250 sensor device.

- In case you have any questions, please do not hesitate to contact your nearest Bosch Sensortec representative for further advice.

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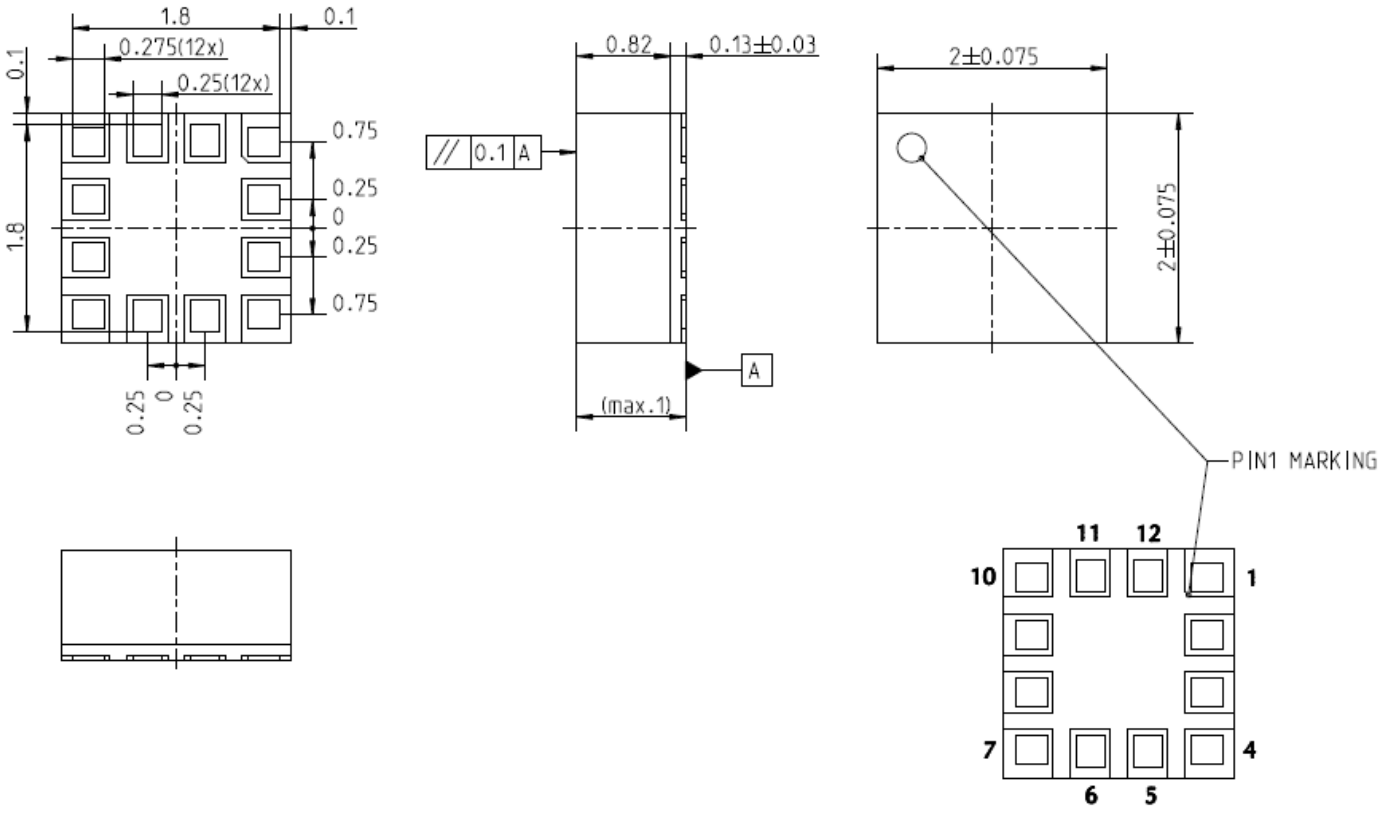
1 Package outline

The BMA250 is packaged in a 2mm x 2mm x 0.95mm LGA package.

Basic outline geometry is based on:

- Mold package footprint 2mm x 2mm
- Height 0.95mm
- No. of leads 12
- Lead pitch 0.5mm

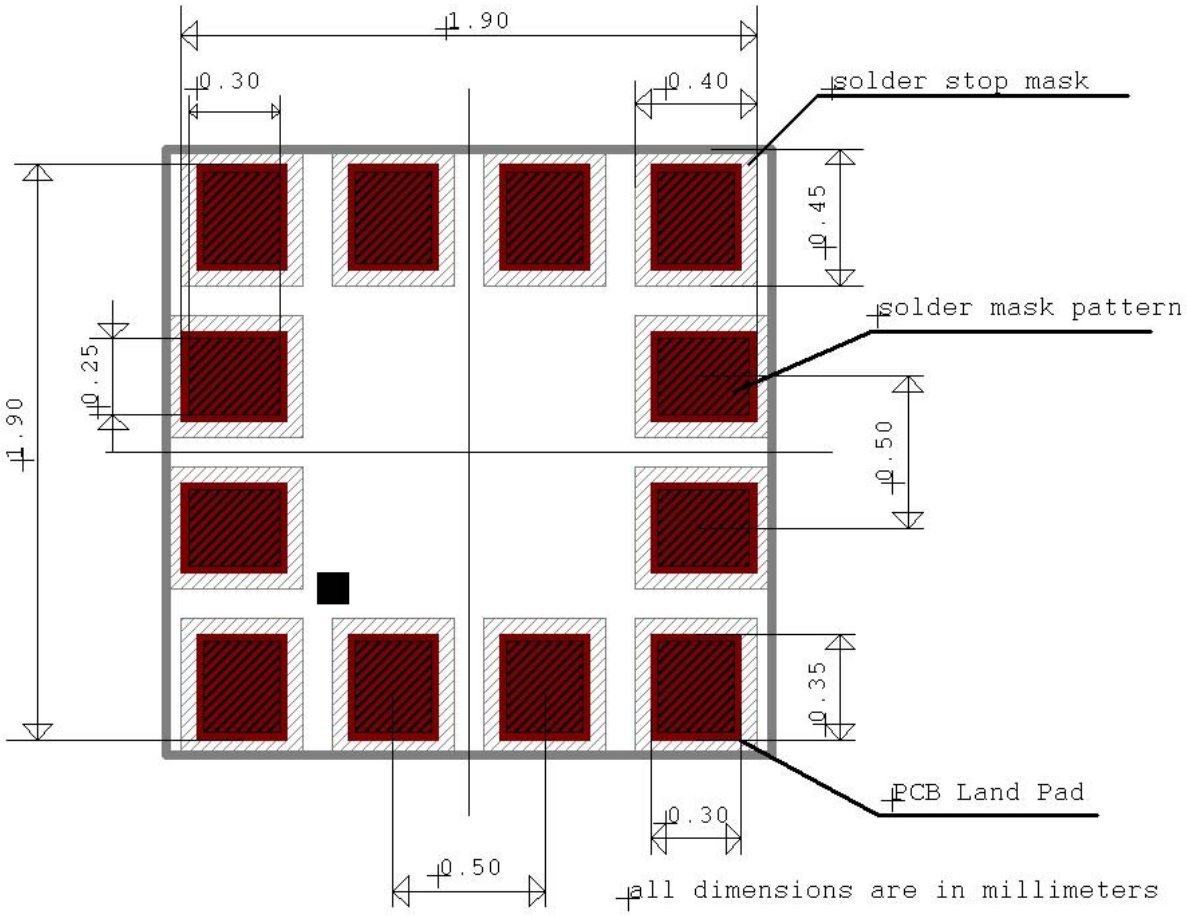
The diagram shows bottom, top and side view of the BMA250's 2mm x 2mm x 0.95mm LGA package (dimensions are in mm).



2 Landing pattern

As for the design of the landing patterns, the following recommendations can be given:

Recommended PCB design / landing pattern (top view):



3 Moisture sensitivity level (MSL)

The moisture sensitivity level (MSL) of the BMA250 sensor IC corresponds to JEDEC level 1, see also

- IPC/JEDEC J-STD-020C "Joint Industry Standard: Moisture/Reflow Sensitivity Classification for non-hermetic Solid State Surface Mount Devices"

- IPC/JEDEC J-STD-033A "Joint Industry Standard: Handling, Packing, Shipping and Use of Moisture/Reflow Sensitive Surface Mount Devices".

The sensor IC fulfils the lead-free soldering requirements of the above-mentioned IPC/JEDEC standard, i.e. reflow soldering with a peak temperature up to 260°C.

4 RoHS compliancy / halogen content

The BMA250 sensor meets the requirements of the EC restriction of hazardous substances (RoHS) directive, see also:

Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

The BMA250 is also halogen-free.

Corresponding chemical analysis certificates are available as separate documents from Bosch Sensortec and via the Bosch Sensortec Extranet web-site.

5 Mounting recommendations

MEMS sensors in general are high-precision measurement devices which consist of electronic as well as mechanical silicon structures. Bosch Sensortec MEMS sensor devices are designed for precision, efficiency and mechanical robustness.

However, in order to achieve best possible results for your design, the following recommendations should be taken into consideration when mounting the sensor on a printed-circuit board (PCB).

The scenarios described below - given as examples – may lead to a bending of the PCB, which as a consequence, might influence the performance of the sensor mounted on the PCB.

In order to evaluate and to optimize the considered placement position of the sensor on the PCB it is recommended to use additional tools during the design in phase, e.g.:

- regarding thermal aspects: infrared camera
- regarding mechanical stress: warpage measurements and/or FEM-simulations

5.1 Recommendations

- It is generally recommended to keep a reasonable distance between the sensor mounting location on the PCB and the critical points described in the following examples. The exact value for a “reasonable distance” depends on many customer specific variables and must therefore be determined case by case.

- It is generally recommended to minimize the PCB thickness (recommended: ≤ 0.8 mm), since a thin PCB shows less intrinsic stress, e.g. while being bent.

- It is not recommended to place the sensor directly under or next to push-button contacts as this can result in mechanical stress.

- It is not recommended to place the sensor in direct vicinity of extremely hot spots regarding temperature (e.g. a µController or a graphic chip) as this can result in heating-up the PCB and consequently also the sensor nearby.

- It is not recommended to place the sensor in direct vicinity of a mechanical stress maximum (e.g. in the center of a diagonal crossover, refer to 5.2.4). Mechanical stress can lead to bending of the PCB and also of the sensor, nearby.

- Do not mount the sensor too closely to a PCB anchor point, where the PCB is attached to a shelf (or similar) as this could also result in mechanical stress. To reduce potential mechanical stress, minimize redundant anchor points and/or loosen respective screws (refer to 5.2.3).

- It is not recommended to mount the sensor in areas where resonant amplitudes (vibrations) of the PCB are likely or to be expected.

- Please avoid partial coverage of the sensor by any kind of (epoxy) resin, as this can possibly result in mechanical stress.
- Avoid mounting (and operation) of the sensor in the vicinity of strong magnetic, strong electric and/or strong infrared radiation fields (IR).
- Avoid electrostatic charging of the sensor and of the device wherein the sensor is mounted.

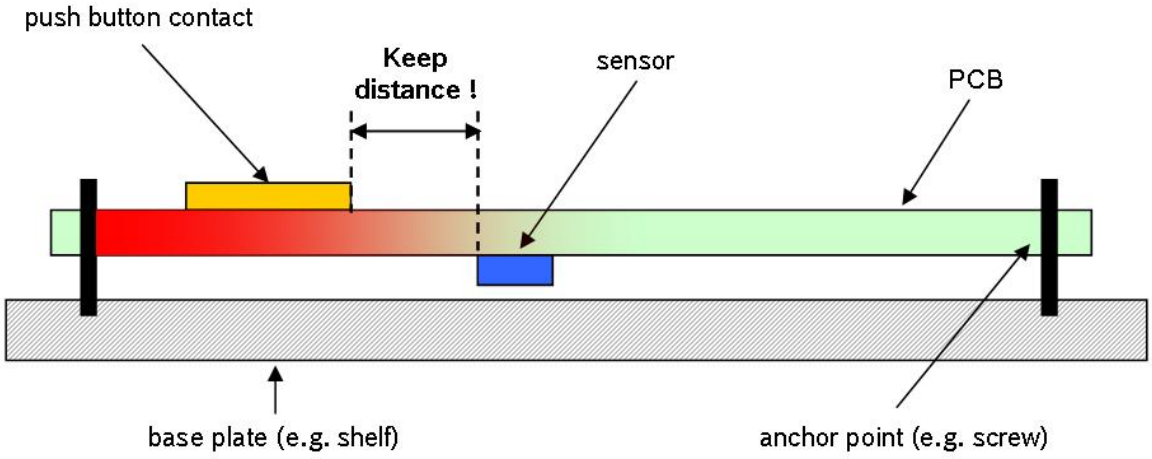
In case you have any questions with regard to the mounting of the sensor on your PCB, or with regard to evaluate and/or to optimize the considered placement position of the sensor on your PCB, do not hesitate to contact us.

If the above mentioned recommendations can not be realized appropriately, a specific in-line offset-calibration after placement of the device onto your PCB might help to minimize potentially remaining effects.

5.2 Recommendation details

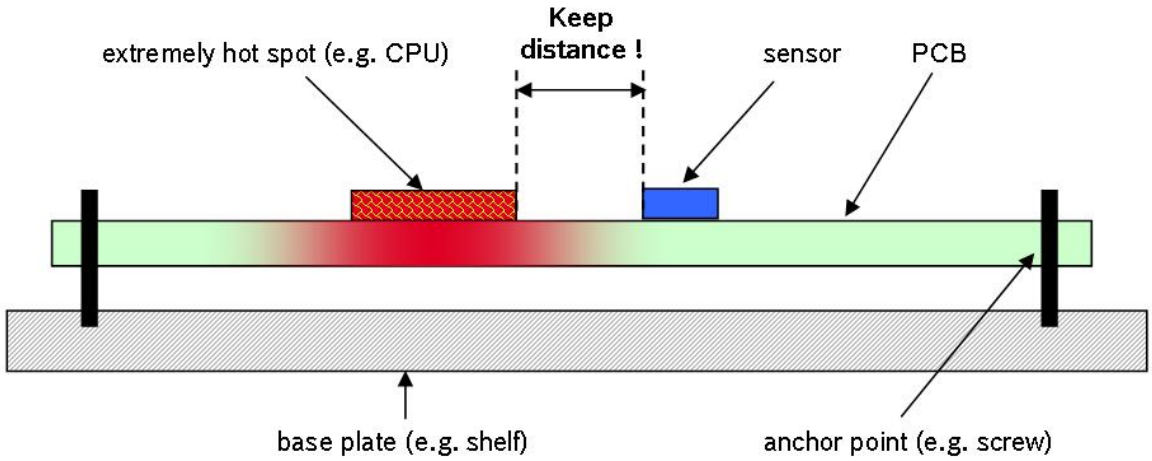
5.2.1 Push-button contacts

Keep a reasonable distance to push-button contacts, when placing the sensor device. Do not position the sensor directly beneath a push-button contact.



5.2.2 Thermal hot-spots on the PCB

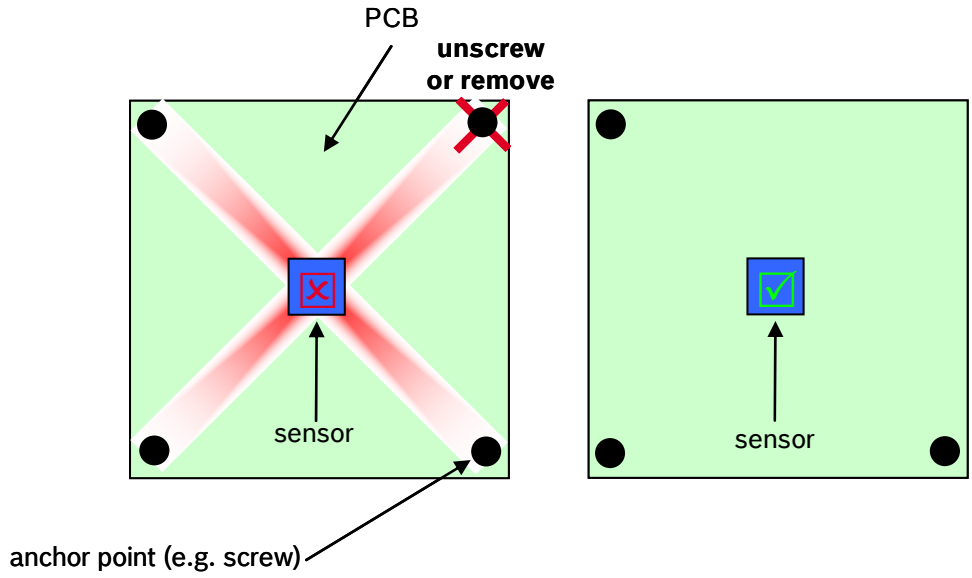
Keep a reasonable distance from any thermal hot spots, when placing the sensor device. Hot spots can for example be other integrated circuits with high power consumption.



5.2.3 Redundant PCB anchor points

It is recommended to unscrew or remove any redundant PCB anchor points. In theory, an ideal flat plane is determined by 3 anchor points, exclusively. Any further anchor point will over-determine the ideal flat plane criteria. If these redundant anchor points are out of plane position (which means not 100% exact in plane position) the ideal flat criteria is infringed, resulting in mechanical stress.

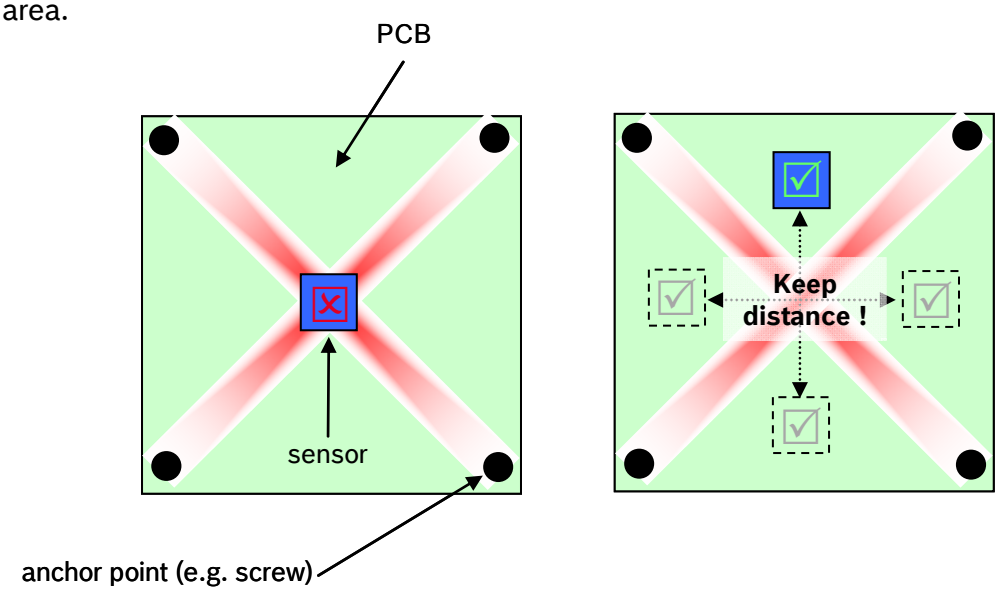
The below given figure describes an expected stress maximum in the center of the diagonal crossover, assuming that the 4 anchor points are not 100% exact in plane (over-determined ideal flat plane criteria). Unscrewing or removing one of the redundant anchor points can minimize mechanical stress, significantly.



5.2.4 Mechanical stress maximum on the PCB

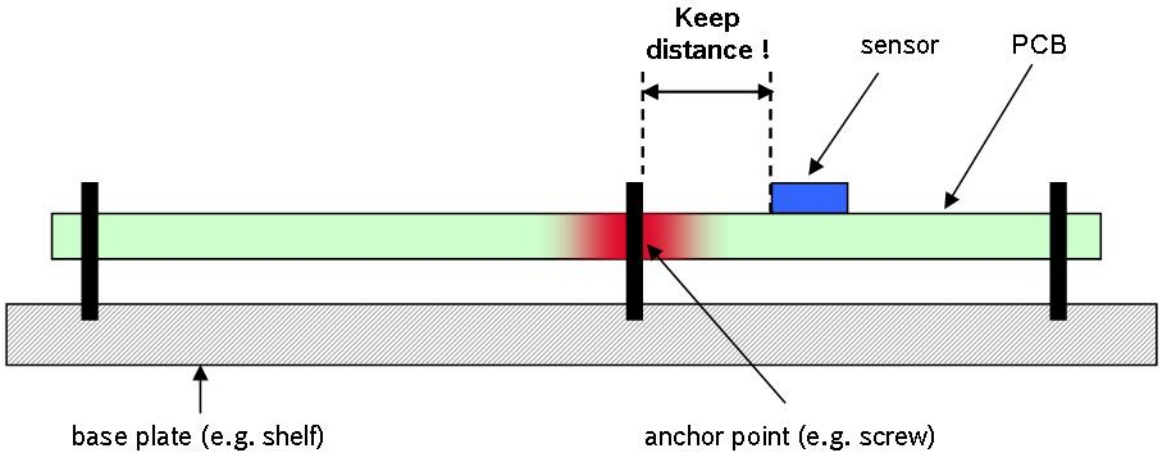
It is recommended to keep a reasonable distance from any mechanical stress maximum, when placing the sensor device. Mechanical stress can be induced for example by redundant anchor points, as described in 5.2.3.

The below given example will show a stress maximum in the center of the diagonal crossover of the 4 anchor points. It is good manufacturing praxis to always avoid or reduce the mechanical stress by optimizing the PCB design first, then to place the sensor in an appropriate low stress area.



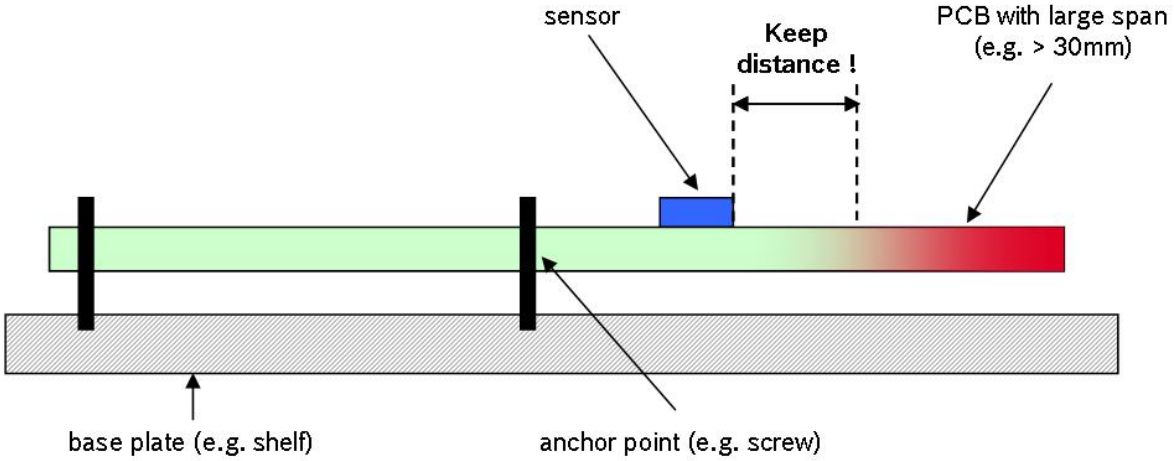
5.2.5 Distance to PCB anchor points

Please keep a reasonable distance from any anchor points, where the PCB is fixed at a base plate (e.g. like a shelf or similar), when placing the sensor device.



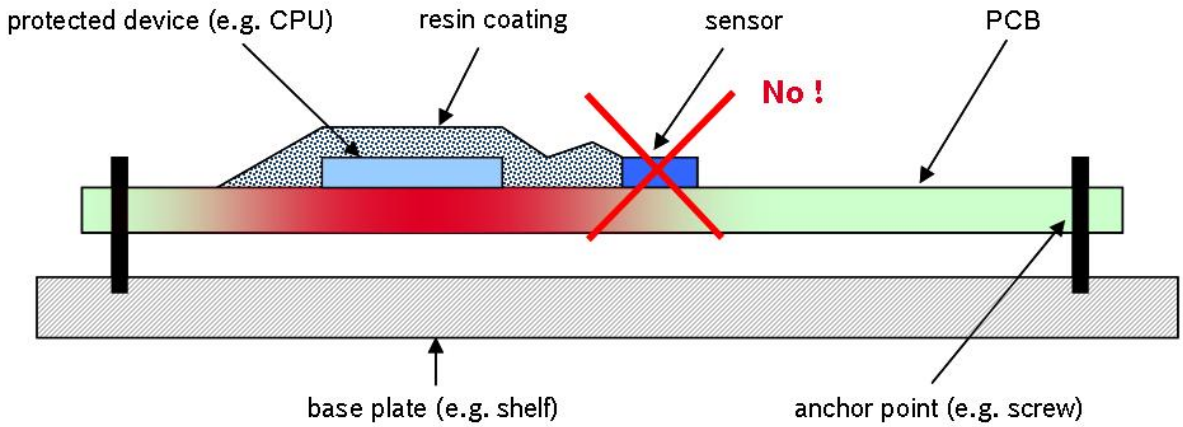
5.2.6 Vibrating PCB

Do not place the sensor in areas where resonant amplitudes (vibrations) of the PCB are likely to occur or to be expected.



5.2.7 Resin coatings

Please avoid partial covering of the sensor with any protective material like for example epoxy resin.



As shown in the above figure, please take care that the sensor (if at all) is not only partially covered and also not in contact with any (epoxy) resign material leading to an un-symmetric stress distribution over the sensor package.

6 Note on internal package structures

Within the scope of Bosch Sensortec's ambition to improve its products and secure the product supply while in mass production, Bosch Sensortec qualifies additional sources for the LGA package of the BMA250.

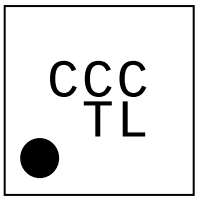
While Bosch Sensortec took care that all of the technical package parameters as described above are 100% identical for both sources, there can be differences in the chemical analysis and internal structural between the different package sources.

However, as secured by the extensive product qualification processes at Bosch Sensortec, this has no impact to the usage or to the quality of the BMA250 product.

7 Device marking

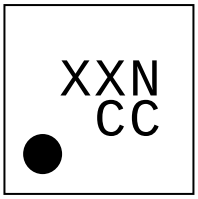
7.1 Mass production samples

Table 1: Marking of mass production samples

Labeling	Name	Symbol	Remark
	Lot counter	CCC	3 alphanumeric digits, variable to generate mass production trace-code
	Product number	T	1 alphanumeric digit, fixed to identify product type, T = “5” or T = “8”
	Sub-con ID	L	1 alphanumeric digit, variable to identify sub-con (L = “A” or L = “U” or L = “P”)
	Pin 1 identifier	●	--

7.2 Engineering samples

Table 2: Marking of engineering samples

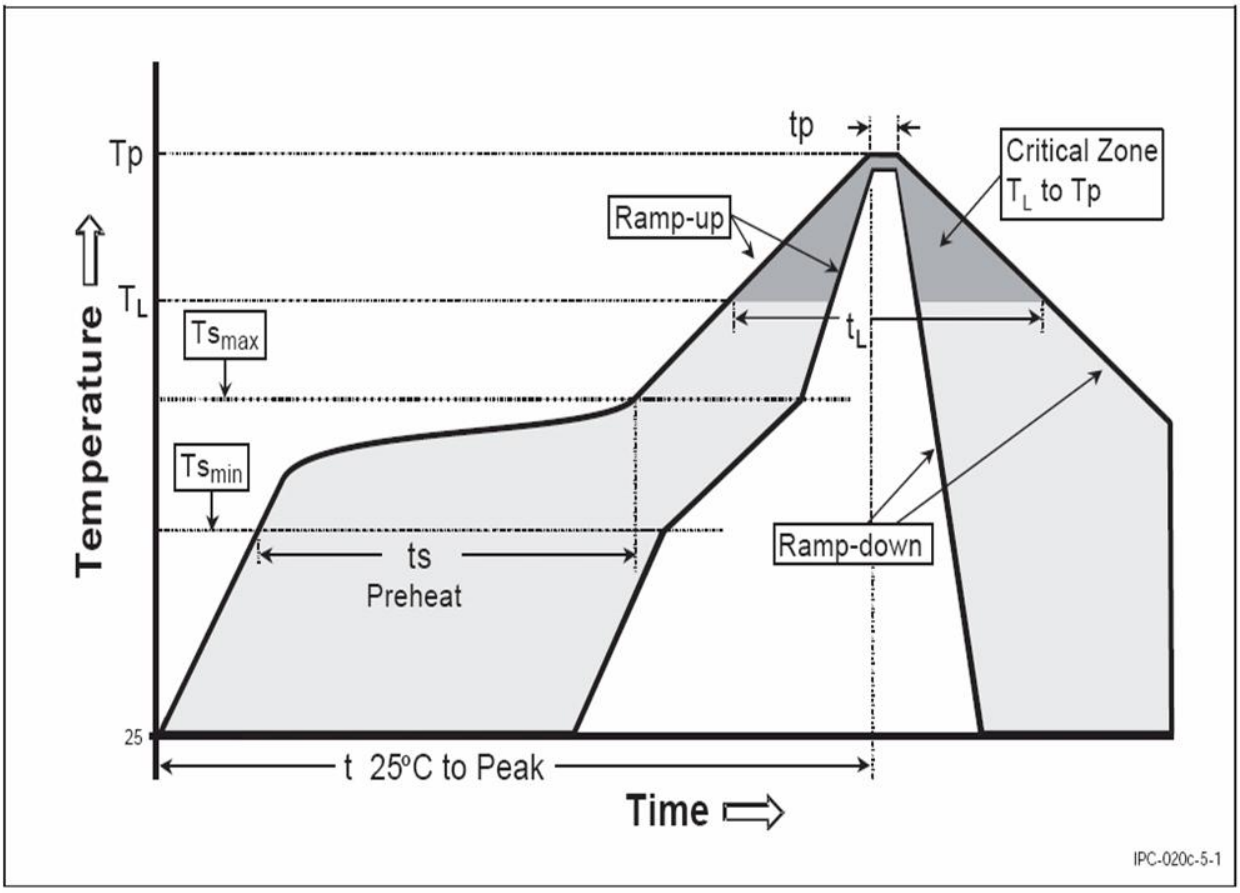
Labeling	Name	Symbol	Remark
	Eng. sample ID	N	1 alphanumeric digit, fixed to identify engineering sample, N = “e”
	Sample ID	XX	2 alphanumeric digits, variable to generate trace-code
	Counter ID	CC	2 alphanumeric digits, variable to generate trace-code
	Pin 1 identifier	●	--

8 Reflow soldering

8.1 Classification reflow profiles

Profile Feature		Pb-Free Assembly
Average Ramp-Up Rate (Ts_{max} to Tp)		3° C/second max.
Preheat – Temperature Min (Ts_{min}) – Temperature Max (Ts_{max}) – Time (ts_{min} to ts_{max})		150 °C 200 °C 60-180 seconds
Time maintained above: – Temperature (T_L) – Time (t_L)		217 °C 60-150 seconds
Peak/Classification Temperature (Tp)		260 °C
Time within 5 °C of actual Peak Temperature (tp)		20-40 seconds
Ramp-Down Rate		6 °C/second max.
Time 25 °C to Peak Temperature		8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package body surface.



8.2 Multiple reflow soldering cycles

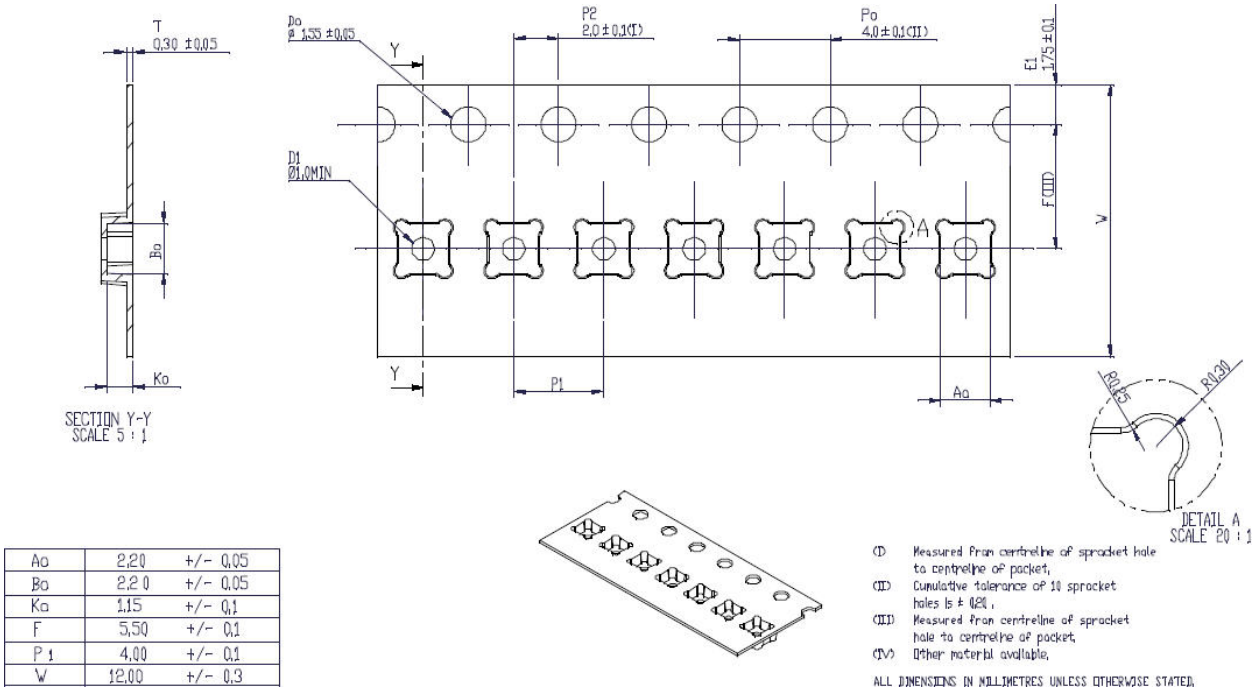
The BMA250 can withstand in total up to 3 reflow soldering cycles.

This could be a situation where a PCB is mounted with devices from both sides (i.e. 2 reflow cycles necessary) and where in the next step an additional re-work cycle could be required (1 reflow).

9 Tape on reel

9.1 Tape and reel specification

The BMA250 is shipped in a standard cardboard box.
The box dimension for 1 reel is: L x W x H = 35cm x 35cm x 6cm
BMA250 quantity: 10,000pcs per reel, please handle with care.



Ao	2,20	+/- 0,05
Bo	2,20	+/- 0,05
Ko	1,15	+/- 0,1
F	5,50	+/- 0,1
P 1	4,00	+/- 0,1
W	12,00	+/- 0,3

Figure 28: Tape and reel dimensions in mm

9.2 Orientation within the reel

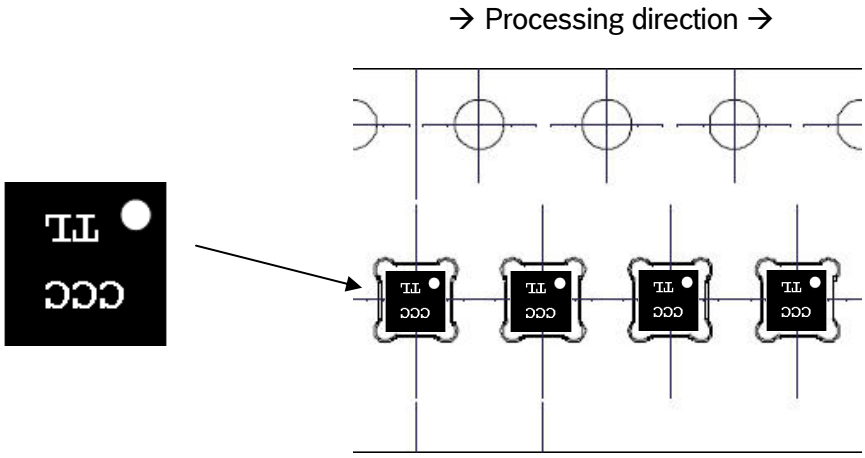


Figure 29: Orientation of the BMA250 devices relative to the tape

10 Further important mounting and assembly recommendations

Micromechanical sensors are designed to sense acceleration with high accuracy even at low amplitudes and contain highly sensitive structures inside the sensor element. The MEMS sensor can tolerate mechanical shocks up to several thousand g's. However, these limits might be exceeded in conditions with extreme shock loads such as e.g. hammer blow on or next to the sensor, dropping of the sensor onto hard surfaces etc.

We strongly recommend to avoid any g-forces beyond the limits specified in the BMA250 data sheet during transport, handling and mounting of the sensors in a defined and qualified installation process.

This device has built-in protections against high electrostatic discharges or electric fields (2kV HBM); however, anti-static precautions should be taken as for any other CMOS component.

Unless otherwise specified, proper operation can only occur when all terminal voltages are kept within the supply voltage range. Unused inputs must always be connected to a defined logic voltage level.

11 Legal disclaimer

11.1 Engineering samples

Engineering Samples are marked with an asterisk (*) or (e). Samples may vary from the valid technical specifications of the product series contained in this data sheet. They are therefore not intended or fit for resale to third parties or for use in end products. Their sole purpose is internal client testing. The testing of an engineering sample may in no way replace the testing of a product series. Bosch Sensortec assumes no liability for the use of engineering samples. The Purchaser shall indemnify Bosch Sensortec from all claims arising from the use of engineering samples.

11.2 Product use

Bosch Sensortec products are developed for the consumer goods industry. They may only be used within the parameters of this product data sheet. They are not fit for use in life-sustaining or security sensitive systems. Security sensitive systems are those for which a malfunction is expected to lead to bodily harm or significant property damage. In addition, they are not fit for use in products which interact with motor vehicle systems.

The resale and/or use of products are at the purchaser's own risk and his own responsibility. The examination of fitness for the intended use is the sole responsibility of the Purchaser.

The purchaser shall indemnify Bosch Sensortec from all third party claims arising from any product use not covered by the parameters of this product data sheet or not approved by Bosch Sensortec and reimburse Bosch Sensortec for all costs in connection with such claims.

The purchaser must monitor the market for the purchased products, particularly with regard to product safety, and inform Bosch Sensortec without delay of all security relevant incidents.

11.3 Application examples and hints

With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Bosch Sensortec hereby disclaims any and all warranties and liabilities of any kind, including without limitation warranties of non-infringement of intellectual property rights or copyrights of any third party. The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. They are provided for illustrative purposes only and no evaluation regarding infringement of intellectual property rights or copyrights or regarding functionality, performance or error has been made.

12 Document history and modification

Rev. no	Chapter	Description of modification/changes	Date
1.0		Document creation	05 October 2010
1.1	5.1	Updated	21 January 2011

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Specifications subject to change without notice
Document number: BST-BMA250-HS000-01
Version_1.1_012011